1-A Output-Current Capability Per Driver
Applications Include Half-H and Full-H
Solenoid Drivers and Motor Drivers
Designed for Positive-Supply Applications
Wide Supply-Voltage Range of 4.5 V to 36 V
TTL- and CMOS-Compatible
High-Impedance Diode-Clamped Inputs
Separate Input-Logic Supply
Thermal Shutdown
Internal ESD Protection

Input Hysteresis Improves Noise Immunity 3-State Outputs

**Minimized Power Dissipation** 

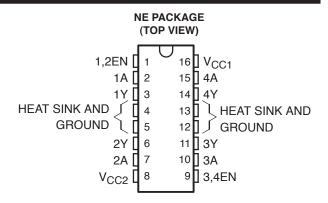
Sink/Source Interlock Circuitry Prevents Simultaneous Conduction

No Output Glitch During Power Up or Power Down

Improved Functional Replacement for the SGS L293

#### description

The SN754410 is a quadruple high-current half-H driver designed to provide bidirectional drive currents up to 1 A at voltages from 4.5 V to 36 V. The device is designed to drive inductive loads such as relays, solenoids, dc and bipolar stepping motors, as well as other high-current/high-voltage loads in positive-supply applications.



## FUNCTION TABLE (each driver)

INP	UTST	OUTPUT
Α	EN	Υ
Н	Н	Н
L	Н	L
X	L	Z

H = high-level, L = low-level

X = irrelevant

Z = high-impedance (off)

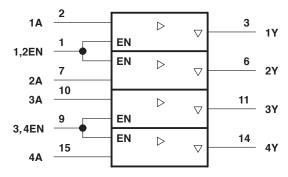
† In the thermal shutdown mode, the output is in a highimpedance state regardless of the input levels.

All inputs are compatible with TTL-and low-level CMOS logic. Each output (Y) is a complete totem-pole driver with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled and their outputs become active and in phase with their inputs. When the enable input is low, those drivers are disabled and their outputs are off and in a high-impedance state. With the proper data inputs, each pair of drivers form a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

A separate supply voltage ( $V_{CC1}$ ) is provided for the logic input circuits to minimize device power dissipation. Supply voltage  $V_{CC2}$  is used for the output circuits.

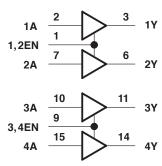
The SN754410 is designed for operation from -40 C to 85 C.

#### logic symbol<sup>†</sup>

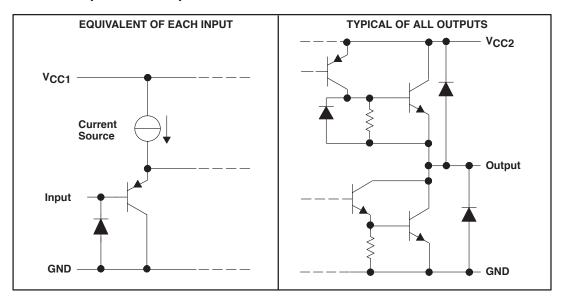


<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram



#### schematics of inputs and outputs



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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Output supply voltage range, V <sub>CC1</sub> (see Note 1)	0.5 V to 36 V
Output supply voltage range, V <sub>CC2</sub>	0.5 V to 36 V
Input voltage, V <sub>I</sub>	36 V
Output voltage range, V <sub>O</sub>	$-3 \text{ V to V}_{CC2} + 3 \text{ V}$
Peak output current (nonrepetitive, $t_W \le 5$ ms)	±2 A
Continuous output current, I <sub>O</sub>	±1.1 A
Continuous total power dissipation at (or below) 25 C free-air temperature (see Note 2)	2075 mW
Operating free-air temperature range, T <sub>A</sub>	40 C to 85 C
Operating virtual junction temperature range, T <sub>J</sub>	40 C to 150 C
Storage temperature range, T <sub>stq</sub>	65 C to 150 C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

	MIN	MAX	UNIT
Output supply voltage, V <sub>CC1</sub>	4.5	5.5	V
Output supply voltage, V <sub>CC2</sub>	4.5	36	V
High-level input voltage, VIH	2	5.5	V
Low-level input voltage, V <sub>IL</sub>	-0.3‡	8.0	V
Operating virtual junction temperature, TJ	-40	125	С
Operating free-air temperature, T <sub>A</sub>	-40	85	С

The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet for logic voltage levels.

NOTES: 1. All voltage values are with respect to network GND.

<sup>2.</sup> For operation above 25 C free-air temperature, derate linearly at the rate of 16.6 mW/ C. To avoid exceeding the design maximum virtual junction temperature, these ratings should not be exceeded. Due to variations in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection can be activated at power levels slightly above or below the rated dissipation.

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# electrical characteristics over recommended ranges of supply voltage and free-air temperature (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP†	MAX	UNIT	
V <sub>IK</sub>	Input clamp voltage	I <sub>I</sub> = -12 mA			-0.9	-1.5	V	
		$I_{OH} = -0$	).5 A	V <sub>CC2</sub> -1.5	V <sub>CC2</sub> -1.1			
$V_{OH}$	High-level output voltage	I <sub>OH</sub> = -1	A	V <sub>CC2</sub> -2			V	
		I <sub>OH</sub> = -1	A, T <sub>J</sub> = 25 C	V <sub>CC2</sub> -1.8	V <sub>CC2</sub> -1.4			
		$I_{OL} = 0.5$	5 A		1	1.4		
$V_{OL}$	Low-level output voltage	$I_{OL} = 1 A$	1			2	V	
		$I_{OL} = 1 A$	$T_{J} = 25 \text{ C}$		1.2	1.8		
V	High level code of class college	I <sub>OK</sub> = -0.5 A			V <sub>CC2</sub> +1.4	V <sub>CC2</sub> +2	V	
VOKH	High-level output clamp voltage	I <sub>OK</sub> = 1 A	4		V <sub>CC2</sub> +1.9	V <sub>CC2</sub> +2.5	V	
V =	Low-level output clamp voltage	I <sub>OK</sub> = 0.5	5 A		-1.1	-2	٧	
VOKL		I <sub>OK</sub> = -1	A		-1.3	-2.5		
	Off-state high-impedance-state	$V_O = V_{CC2}$				500	^	
I <sub>OZ(off)</sub>	output current	$V_O = 0$				-500	Α	
lіН	High-level input current	V <sub>I</sub> = 5.5 V				10	Α	
I <sub>I</sub> L	Low-level input current	V <sub>I</sub> = 0				-10	Α	
I <sub>CC1</sub>	Output supply current		All outputs at high level			38		
		$I_O = 0$	All outputs at low level			70	mA	
			All outputs at high impedance			25	1	
I <sub>CC2</sub>	Output supply current		All outputs at high level			33		
		$I_O = 0$	All outputs at low level	20 e 5		20	mA	
			All outputs at high impedance			1		

 $<sup>^{\</sup>dagger}$  All typical values are at V<sub>CC1</sub> = 5 V, V<sub>CC2</sub> = 24 V, T<sub>A</sub> = 25 C.

### switching characteristics, $V_{CC1}$ = 5 V, $V_{CC2}$ = 24 V, $C_L$ = 30 pF, $T_A$ = 25 C

	PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
t <sub>d1</sub>	Delay time, high-to-low-level output from A input		400		ns
t <sub>d2</sub>	Delay time, low-to-high-level output from A input		800		ns
tTLH	Transition time, low-to-high-level output		300		ns
t <sub>THL</sub>	Transition time, high-to-low-level output	See Figure 1	300		ns
t <sub>f</sub> Rise time, pulse input t <sub>f</sub> Fall time, pulse input					
t <sub>W</sub>	Pulse duration				
t <sub>en1</sub>	Enable time to the high level		700		ns
t <sub>en2</sub>	Enable time to the low level	See Figure 2	400		ns
t <sub>dis1</sub>	Disable time from the high level		900		ns
t <sub>dis2</sub>	Disable time from the low level		600		ns

#### PARAMETER MEASUREMENT INFORMATION

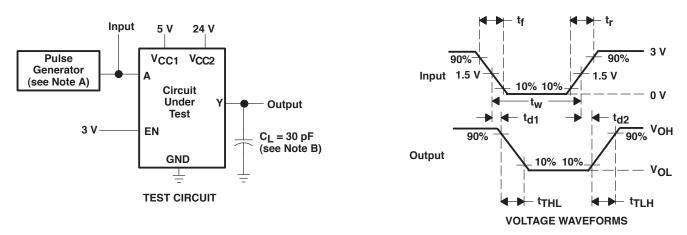


Figure 1. Test Circuit and Switching Times From Data Inputs

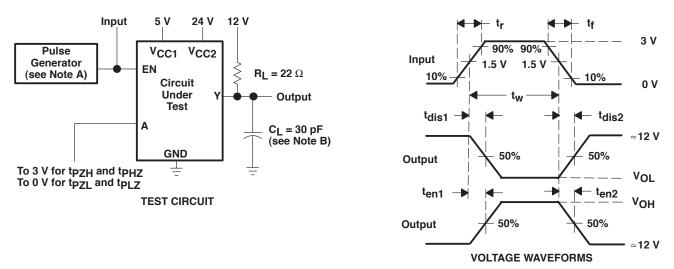


Figure 2. Test Circuit and Switching Times From Enable Inputs

NOTES: A. The pulse generator has the following characteristics:  $t_{f} \le 10$  ns,  $t_{f} \le 10$  ns,  $t_{W} = 10$  s, PRR = 5 kHz,  $Z_{O} = 50$   $\Omega$ .

B. C<sub>L</sub> includes probe and jig capacitance.

#### **APPLICATION INFORMATION**

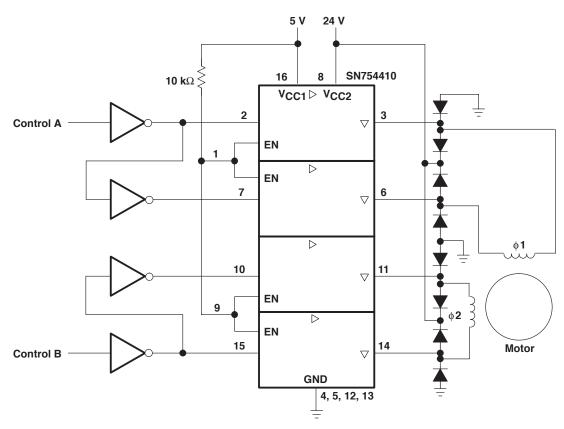


Figure 3. Two-Phase Motor Driver



#### PACKAGE OPTION ADDENDUM

12-Jan-2006

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN754410NE	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN754410NEE4	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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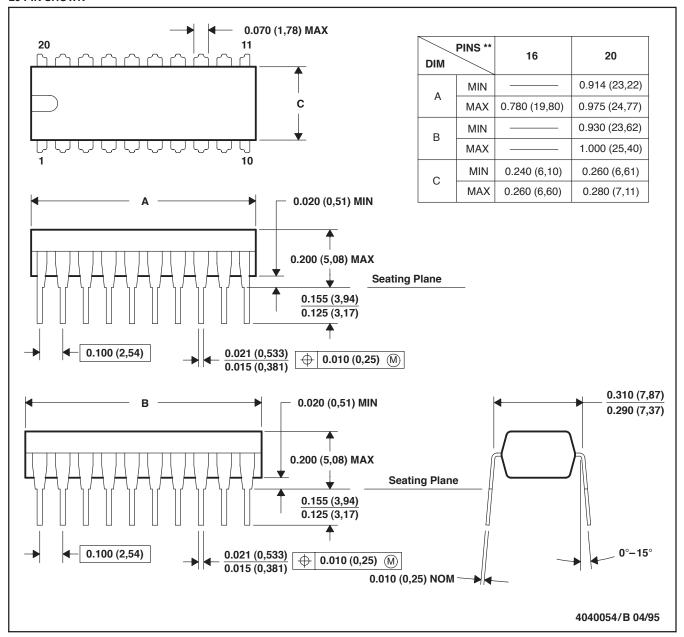
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#### NE (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

#### 20 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-001 (16 pin only)

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